Materials Declaration

Package	MQFP
Body Size	14 X 20
LeadCount	128
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	9.85 E-02	50678
SiO2 Filler	86	1.06 E+00	544787
Phenol Resin	5	6.16 E-02	31674
Antimony_Sb2O3	0.4	4.93 E-03	2534
Brominated Resin	0.4	4.93 E-03	2534
Carbon Black	0.2	2.46 E-03	1267

Molding Compound

Item	PPM	Method
Pb	4.90	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.17 E-01	214685
Ni	3	1.30 E-02	6695
Si	0.65	2.82 E-03	1451
Mg	0.15	6.51 E-04	335

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-03	1543

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.11 E-02	10834

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.80 E-03	1956

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	2.33 E-01	119913

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.61 E-03	2370
Ag Filler	74	1.31 E-02	6745

Package Totals

Weight (g)	PPM
1.94 E+00	1000000

STS-S-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc any inaccuracy of such information.

ADI Proprietary

04/26/04

Materials Declaration

Package	MQFP
Body Size	14 X 20
LeadCount	128
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	9.85 E-02	50678
SiO2 Filler	86	1.06 E+00	544787
Phenol Resin	5	6.16 E-02	31674
Antimony_Sb2O3	0.4	4.93 E-03	2534
Brominated Resin	0.4	4.93 E-03	2534
Carbon Black	0.2	2.46 E-03	1267

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.17 E-01	214685
Ni	3	1.30 E-02	6695
Si	0.65	2.82 E-03	1451
Mg	0.15	6.51 E-04	335

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-03	1543

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.79 E-02	9209
Pb	15	3.16 E-03	1625

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.80 E-03	1956

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	2.33 E-01	119913

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.61 E-03	2370
Ag Filler	74	1.31 E-02	6745

Package Totals

Weight (g)	PPM
1.94 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	4.90	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-S-A

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